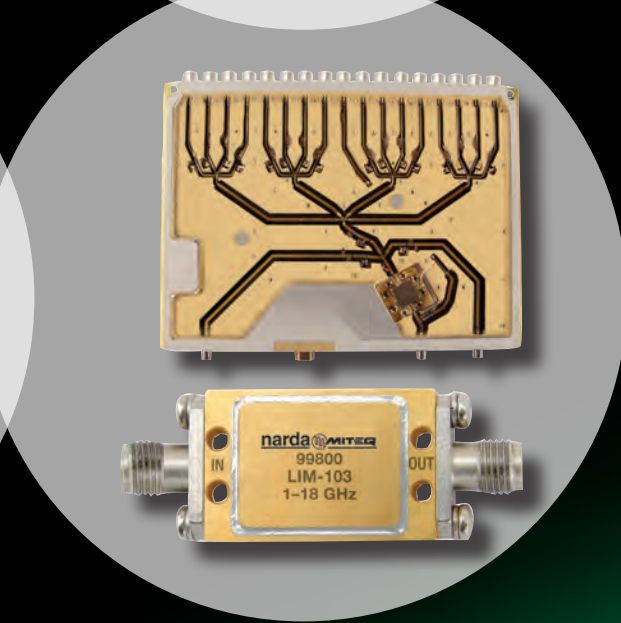
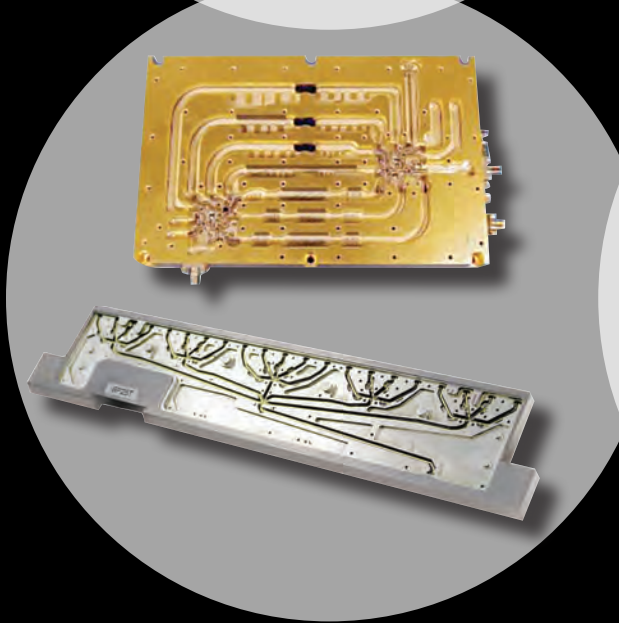
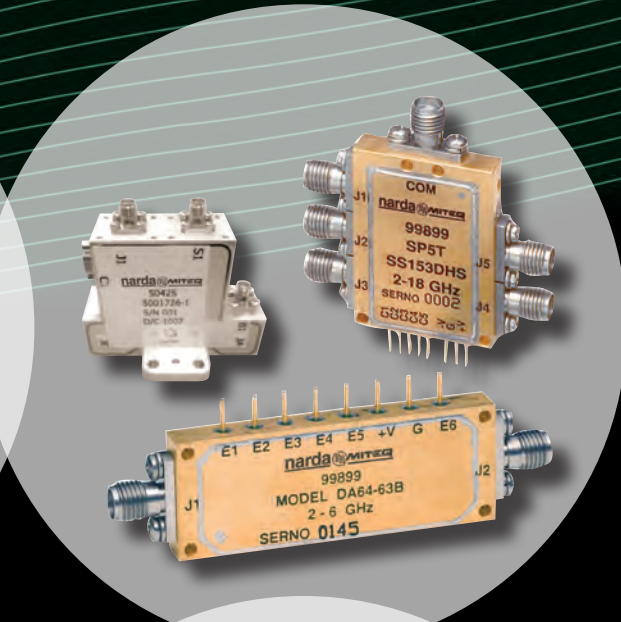
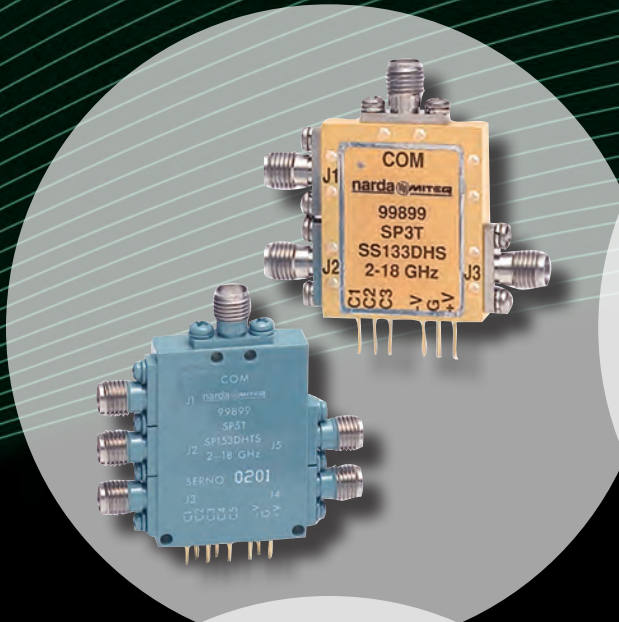


APPLICATION NOTE AND SHORT-FORM CATALOG



- PIN DIODE SWITCHES
- PIN DIODE ATTENUATORS
- PIN DIODE LIMITERS
- PIN DIODE BASED IMAs

OVERVIEW

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Narda-MITEQ has more than 60 years of experience in serving both the military and commercial markets with outstanding RF and microwave products. Our design and world-renowned manufacturing facility has more than 235,000 square feet, housing our dedicated team of sales, design and production professionals. We are ready to design, develop and deliver high-performance products to address your needs.

With the development and manufacture of state-of-the-art RF and microwave components, integrated microwave assemblies, subsystems and world-renowned SATCOM equipment, Narda-MITEQ has positioned itself as a technology leader by offering advanced products in the frequency range of DC to 100 GHz for both commercial and military applications. We maintain the world's largest inventory of RF and microwave components for the rapid delivery of products to our customer base. Component products manufactured at our production facility include IMAs, couplers, power dividers, attenuators, RF switches, power monitors, amplifiers, mixers, frequency multipliers, fiber-optics, frequency generation, IF signal processing, PIN limiters and terminations that are suitable for a myriad of RF applications. SATCOM products manufactured at our facility include synthesized frequency converters, single and multiband block converters, test translators, LNAs and LNBs, equalizers, uplink power control products, fiber-optic products and custom SATCOM solutions.

Narda-MITEQ's portfolio of products also includes RF safety test solutions that characterize emission levels for RF workers and the general public.

PIN DIODE INTRODUCTION

RF and microwave components based on PIN diodes have been essential tools in the designer’s toolkit for decades, and with good reason: their unique characteristics make them the best choice for a wide variety of control applications, such as switches, attenuators, phase shifters, limiters and modulators.

PIN diodes are fundamentally similar to standard diodes, but have an RF impedance that is determined by an externally supplied bias current. Their versatility makes them excellent building blocks in a wide variety of configurations within each product category, which allows diverse system requirements to be served. In short, the PIN diode enables all systems – from the least complex to the most sophisticated – to achieve their intended missions, while requiring very little space, power or cost.

There are many resources that provide both practical and theoretical information about PIN diode theory, characteristics and incorporation in modules and subsystem designs. However, practical information about choosing the proper PIN diode-based product for a specific application is conspicuously absent. RF and Microwave PIN Control Product Application and Selection has been created to fill this void. It includes basic discussions of PIN diode characteristics, the most commonly used PIN diode-based products, and the trade-offs encountered in designing products around them. The merits of various types of control products within a specific category (analog and digital attenuators, for example) are discussed as well.

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PIN DIODE SWITCHES

PIN DIODE SWITCHES

Switches that control the path of RF power from low frequencies through the low millimeter-wave range are the most common application for PIN diodes. The level of DC bias applied to the diode determines its impedance. In the case of a PIN diode-mounted in series with a transmission line, when the bias changes the impedance from a low value to a high value, the circuit acts as a switch. That is, the switch is in the on state when forward-biased (low impedance), and in the off state when zero or reverse-biased (high impedance). The attenuation produced by the diode switch is called insertion loss (IL) when the switch is in the on state, and isolation when in the off state.

In a simple SPST PIN diode switch (Figure 1), the diode can be either series- or shunt-connected. The series-connected PIN diode configuration can provide reasonably low insertion loss over a multi-octave frequency range, but with lower power-handling capability. Design and fabrication are also simpler because no holes are required in the circuit board to mount shunt diodes. In series diode switches, insertion loss is dependent on the series resistance of the PIN diode while isolation is primarily dependent on the junction capacitance. These parameters are determined by the forward-biased current and reverse-biased voltage, respectively.

The shunt-connected PIN diode configuration optimizes high-isolation and low loss across a wide frequency range (up to several octaves), and can handle higher-power levels because the diodes are mounted directly to the housing. The shunt switch is on when the diode is zero or reverse-biased, and off when forward-biased (the opposite of the series switch).

The insertion loss of a shunt-connected diode at a given frequency is primarily dependent on its junction capacitance (C_j), while the isolation provided by the diode is dependent on its series resistance (R_s) when the diode is forward-biased. A combination series-shunt topology is also used and provides very wideband performance, high speed and moderate power-handling ability and insertion loss.

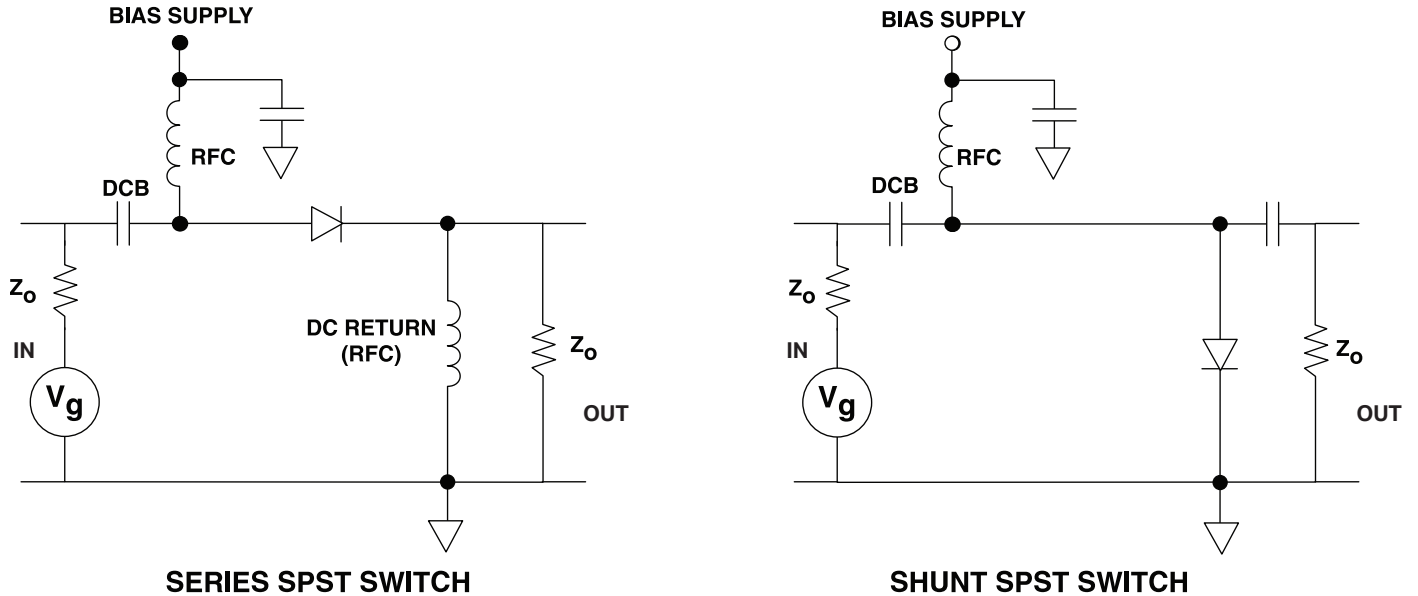


Figure 1-Simple SPST PIN Diode Switches

Multi-throw switches can be configured in two ways to achieve improved performance. In the first method (Figure 2a), PIN diodes series-connected to the common junction and the diodes in the On port are forward-biased while the remaining diodes are reverse-biased. The result is a low-loss path for the On port and minimal loading by the Off port.

In the second method (figure 2b), shunt-connected PIN diodes are placed one-quarter wavelength from the common junction, and the selected diodes of the On port are reverse-biased while the Off port are forward-biased. The result in this case is an electrical short across each Off transmission line, and the quarter-wavelength spacing transforms the shorts to open circuits at the junction.

These techniques are optimized through prudent choice of transmission line impedances while keeping stray reactance low, resulting in a switch with acceptably low-insertion loss and VSWR, and a 3:1 bandwidth.

While it is possible to achieve isolation somewhat greater than 40 dB with a single PIN diode (either series- or shunt-connected) at lower microwave frequencies, it is typically necessary at higher frequencies to increase the number of switch elements by using additional series-mounted and shunt-connected PIN diodes in each arm.

The isolation elements of a switch (series or shunt diodes) are usually spaced a quarter-wavelength apart. This results in a value of isolation 6 dB greater than the sum of the isolation that is provided by each pair of diodes. This structure can be repeated several times to achieve greater than 90 dB isolation.

Insertion loss, isolation, switching speed and power handling ability are typically the parameters used to describe switch performance. However, there are other key parameters.

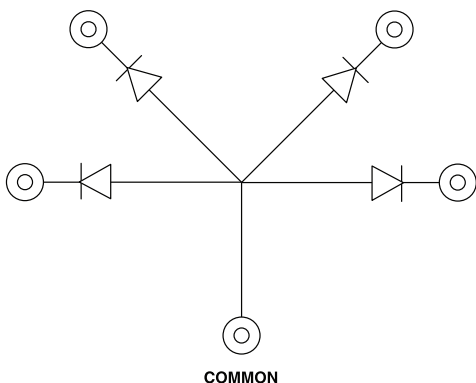


Figure 2a - Series diodes at common junction

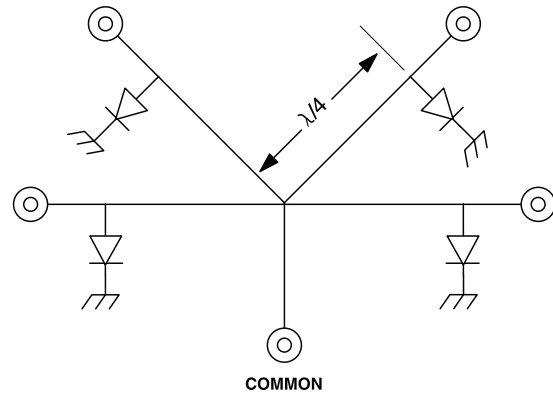


Figure 2b - Shunt diodes located quarter-wavelength from common junction

VIDEO LEAKAGE

The spurious signals at the switches RF ports when there is no RF signal present are collectively called video leakage. The switch driver produces these signals, specifically at the leading edge of the voltage spike provided for high-speed switching. There can actually be video spikes of ± 10 VDC present in a system with a 50 ohm impedance, although ± 1.5 to ± 3.0 VDC is more common. Most of the RF energy in the video spike is below 200 MHz but in very high-speed, broadband switches, there can be appreciable RF energy (-60 dBm to -50 dBm) produced – as high as 1 GHz. High-pass filters can reduce the level of low-band video leakage components, but signals within the passband of the switch (inband video leakage) cannot be filtered out. Inband video leakage can be reduced only by using a switch with a slower switching speed or by very carefully tailoring the drive waveform to suit the particular type of PIN diode being used.

PIN DIODE SWITCHES

HARMONICS AND DISTORTION

PIN diodes, like all diodes, are nonlinear in their response characteristics, and as a result produce harmonics and intermodulation distortion (IMD) products. Fortunately, these products are usually at very low levels in a PIN diode switch because the diodes themselves are either in a saturated, forward-biased condition or are reversed-biased. The minority carrier lifetime of the diode determines the level of IMD. A PIN diode switch's IMD performance is usually described by its third-order output intercept point (OIP). Good OIP performance for typical PIN switches ranges from +35 dBm to +45 dBm. The level of harmonics and IMD varies widely among devices, so it is important to read the manufacturer's specifications for these parameters for every model considered.

MINORITY CARRIER LIFETIME

This specification is very important from the perspective of both diode and circuit design. Carrier lifetime (TL) is a property of the semiconductor material, and when the PIN diode is forward-biased, injection of electrons and holes occurs from the N+ and P+ contacts respectively. These carriers have a finite lifetime, and the average time before they recombine is the carrier lifetime.

Recombination takes place through interaction between the crystal lattice and impurities in the I region and P+ and N+ regions of the diode. The carrier lifetime in a PIN diode controls the switching speed, i.e., the time required to switch the diode from a low-impedance forward-bias state to a high-impedance reverse-bias state. This transition is the slower of the two transitions in a switching application since the driver circuit is attempting to remove stored charge from the PIN diode.

Switching speed and minority carrier lifetime are directly related. To visualize their interaction, it helps to examine the relationship of minority carrier lifetime and its forward and reverse current ratio (I_f/I_r) in the following equation:

$$T_{rr} = T_L \log(1 + I_f / I_r)$$

where

T_{rr} is the diode's switching speed (commonly referred to as Reverse Recovery Time), and T_L is the minority carrier lifetime.

This equation describes the dependence of switching time on the minority carrier lifetime and the I_f / I_r ratio.

SWITCHING SPEED (MODULATION OR COMMUTATION)

Rise Time And Fall Time: These parameters, fundamental to many designs, are actually composed of several subsets, each one defining the time required for switching to take place between two states in the switch response (Figure 3a). Rise time is defined as the period between full Off and full On, specifically from 10 percent of this condition to 90 percent of the square-law-detected RF power. Conversely, fall time is the period between 90 percent of full On to 10 percent of full Off. Rise time and fall time does not include driver propagation delays.

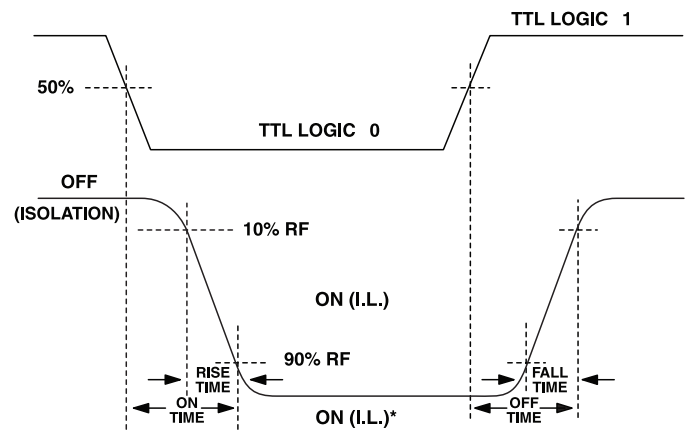


Figure 3a - Detected RF power, rise time and fall time

MODULATION ON TIME AND OFF TIME

The time lapse between 50 percent of the input control signal from the driver to 90 percent of the square-law-detected RF power when the device is switched from full Off to full On is called the On time. The Off time begins when the 50 percent point of control signal occurs, to the point when it achieves 10 percent of its square-law detected RF power and the unit is switched from full On to full Off. On and Off times include driver propagation delays. This is sometimes referred to as Modulation Time.

COMMUTATION (PORT-TO-PORT TIME SWITCHING TIME)

(Figure 3b), sometimes referred to as Commutation Time, is the period from when the RF power level at the off-going port falls to 10 percent of its original level to the time the RF power in the ongoing port rises to 90 percent of its final value. In high-speed, reflective switches, commutation time is typically slightly longer than On or Off time. For absorptive switches, commutation time can be much longer than On or Off time, please consult the factory.

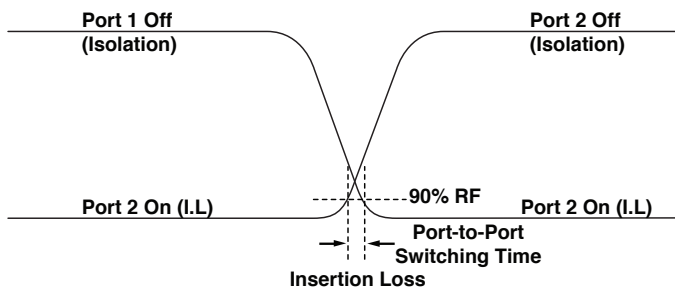


Figure 3b - Port-to-port switching time

ALL SPECIFICATIONS FOR SWITCHING SPEED IN THE NARDA-MITEQ CATALOG ARE FOR MODULATION SWITCHING SPEED.

PERFORMANCE TRADE-OFFS

The design of any subsystem invariably requires trade-offs in one or more areas of performance. Optimizing a design for one performance parameter often occurs at the expense of another. Such is the case with PIN diode switches.

POWER vs. FREQUENCY

Junction capacitance can be reduced in order to ensure low loss at higher operating frequencies. For a given switching speed, junction capacitance can be lowered by decreasing the area of the diode. This increases the diodes thermal impedance, producing a reduction in power-handling ability.

POWER vs. SWITCHING SPEED

To optimize power-handling ability, the diodes junction area must be large (hence lower thermal impedance). This increases the diodes junction capacitance, resulting in higher insertion loss, lower isolation (in a series switch configuration), and usually smaller bandwidths. To maintain low capacitance, the diodes I-region thickness must be increased to compensate for the increase in capacitance caused by the increased junction area. The increased length of the I region raises the minority carrier lifetime, which increases switching speed. An added benefit of increasing the diode junction area is a reduction in its forward-biased resistance, improving isolation in a shunt switch.

FREQUENCY AND BANDWIDTH

For a shunt configuration, the insertion loss (in dB) caused by the diode is given by:

$$10 \log [1 + 2 (Z_0 \pi F C_j)^2] \text{ for reverse-bias}$$

As the diode capacitance increases, the switches insertion loss increases dramatically.

For a shunt configuration, the switch isolation (in dB) is given by:

$$20 \log \left[1 + \frac{Z_0}{2R_s} \right] \text{ for forward-bias}$$

where

Z_0 is the circuit's characteristic impedance

F is the RF frequency of interest

C_j is the diodes junction capacitance

R_s is the diodes forward-bias resistance

PIN DIODE SWITCHES

REFLECTIVE SWITCHES

A reflective switch is one in which the incident power at the Off port is reflected back to the source as a result of the impedance mismatch presented by the PIN diode. In contrast, an absorptive switch is designed to present a 50 ohm impedance in the Off state and to absorb incident power.

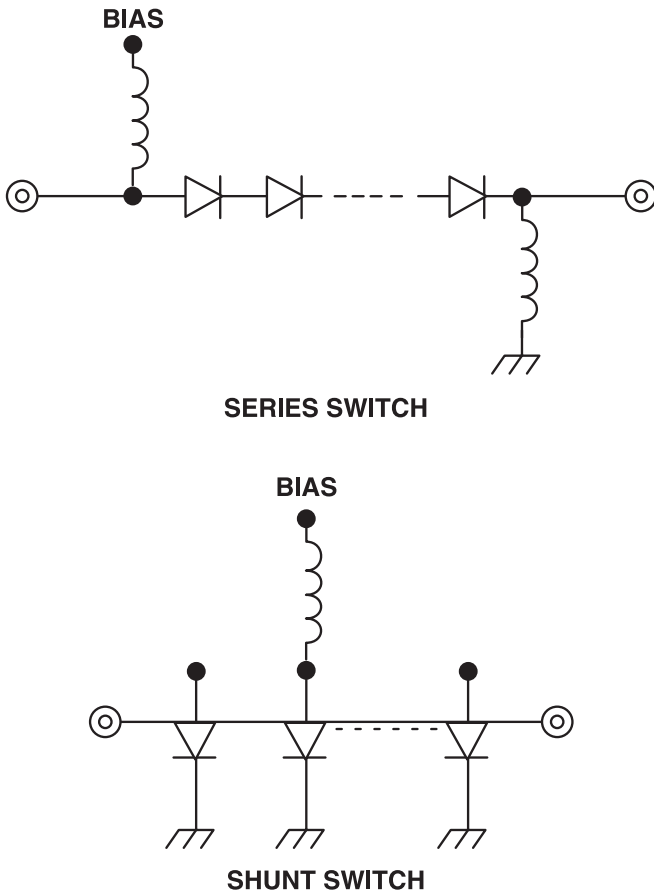


Figure 4 - Series and shunt reflective switches

Typical reflective switches (Figure 4) include the previously described SPST series configuration and an all-shunt arrangement, with its inherently higher power-handling ability and switching speed. The operating bandwidth of the switch is determined by the blocking capacitors selected, the bias circuitry and the diodes reverse-bias capacitance. Reducing the diodes shunt resistance increases isolation in this type of switch. This reduction is achieved either by increasing the current or decreasing the diodes overall resistance. In addition, by adding a fourth shunt diode, isolation can be increased, which is accompanied by an increase in insertion loss, but with little impact on power handling and switching speed.

MULTI-THROW REFLECTIVE SWITCHES

Taking this design to a multi-throw configuration (Figure 5), the low insertion loss at the On port must be isolated from the high insertion loss at the Off port with a series PIN diode. Isolation at the Off port is a function of frequency and diode capacitance, and isolation will increase as the capacitance of the series diode decreases. However, increased bandwidth (lower capacitance) comes at the expense of reduced power-handling ability. The number of throws can be extended in this type of switch, limited only by the diodes junction capacitance and the physical size limitations of the switch.

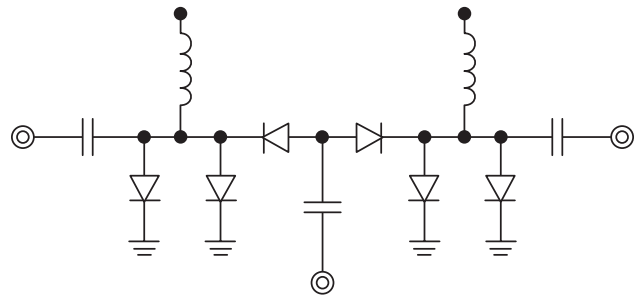


Figure 5 - Multi-throw reflective SPDT switch

ABSORPTIVE SWITCHES

Multi-throw absorptive switches either employ the series-shunt approach (Figure 6). The required 50 ohm terminating impedance is achieved by the series combination of the diode and terminating resistance to ground. This type of termination has good high-frequency characteristics, but power-handling ability is limited by the ability of the diodes and resistors to dissipate RF power. In addition, absorptive switches typically exhibit somewhat slower switching speeds. These types of switches are usually not absorptive at their common port (in the All-Off state) but can be made absorptive for special applications.

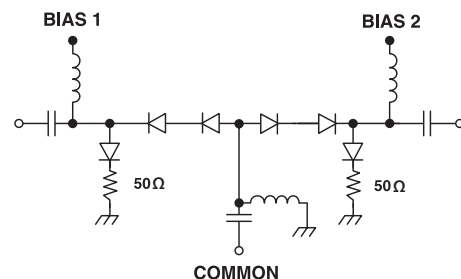


Figure 6a - Absorptive SPDT switches, shunt termination

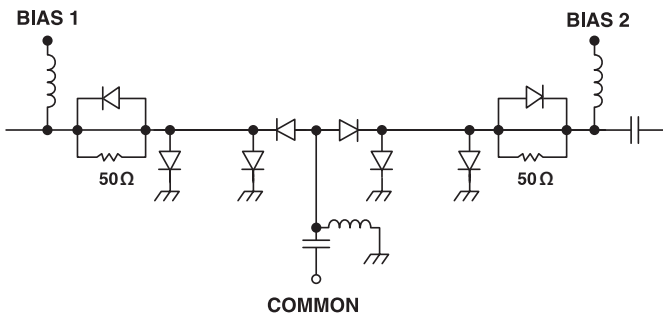


Figure 6b - Absorptive SPDT switches, series termination

TRANSMIT/RECEIVE (T/R) SWITCHES

T/R switches are used to switch a single feedline between a transmitter and receiver and can benefit greatly from PIN diode switch technology. They are more reliable, faster and more rugged than their electro-mechanical counterparts. The basic T/R switch consists of a PIN diode connected in series with the transmitter and a shunt diode connected one quarter-wavelength away from the antenna in the direction of the receiver section (Figure 7). Of course, quarter-wavelength spacing is not practical at low frequencies, so quarter-wavelength lumped elements can be used instead. In T/R switches, the trade-off is between achieving low loss for the receiver path and high power-handling ability for the transmitter path.

When the switch transfers the feedline to the transmitter, each diode becomes forward-biased. The series diode appears as a low impedance to the signal approaching the antenna, and the shunt diode shorts the receiver's antenna terminals to prevent overload. Transmitter insertion loss and receiver isolation are dependent on the diode resistance. In the receive condition, the diodes are zero or reverse-biased, and present a low (shunt) capacitance which creates a low-loss path between the antenna and receiver. The Off (transmitter) port is isolated from this path by the high-impedance series diode.

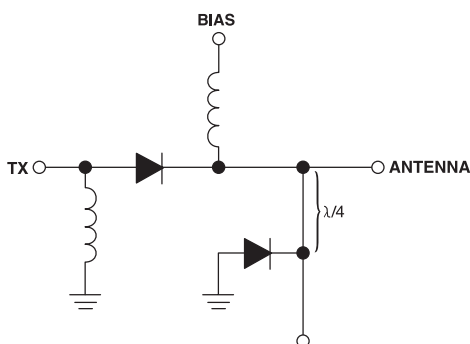


Figure 7 - Transmit/Receive switch

A WORD ON DRIVERS

A PIN diode switch will perform only as well as its driver allows. The driver must be capable of supplying the necessary reverse-bias voltage in order to achieve the desired diode capacitance, and must source or sink the bias currents required to drive the diodes to their rated forward-bias resistance. In addition, fast-switching requires the transition time between driver output levels to be as short as possible. Relatively high-voltage spikes are also required to remove charge from forward-bias diodes and speed up their switching time.

From the user's perspective, the important parameters are:

- Switching speed and repetition rate
- Number of switch throws
- Number of control lines (i.e., one line per throw or integral switch logic decoders)
- Logic sense (Ø = low-loss state is typical)
- Driver integral to switch assembly or mounted separately. High-speed switch-driver circuits are usually built as hybrid (chip and wire) circuits to reduce size and increase speed, and mounted next to the RF section.

PIN DIODE ATTENUATORS

INTRODUCTION

PIN diode attenuators range from simple series connected or shunt-connected diodes acting as a lossy reflective switch to more complex structures that maintain a good input match across the full dynamic range of the attenuator. PIN diode attenuator circuits are used extensively in automatic gain control (AGC) and RF leveling applications. Although other methods are available for providing AGC, such as varying the gain of the RF amplifier, the PIN diode approach results in lower power drain, less frequency pulling, and lower RF signal distortion. Lower attenuator distortion is achieved using diodes with thicker I-regions and long carrier lifetimes.

In an attenuator, the resistance characteristics of the diode are exploited not only at their extreme high and low values as switches, but also at values in between. Thus, PIN diode attenuators tend to produce less distortion than amplifiers but more than switches. The resistance characteristic of a PIN diode when forward-biased depends on the I-region thickness, carrier lifetime, and hole and electron mobilities. A PIN diode with a thin I-region will operate at lower forward-bias currents than a PIN diode with a thick I-region, but the latter diode will generate less distortion. Careful selection of diode I-layer thickness can yield a good compromise between attenuator speed, distortion, linearity, and power-handling ability. In addition, it is easier to linearize the driver for thicker diodes

NOTES ON ATTENUATOR PERFORMANCE

Understanding how the following parameters affect performance makes it easier to choose the best type of attenuator for a particular application.

PHASE SHIFT AND ATTENUATION

A PIN diode attenuator phase shift varies as the attenuation level changes. This is a result of stray PIN diode reactance vs. bias level, or (in the case of a switched-BIT attenuator) the different lengths of the transmission paths connecting the diodes that are being switched in or out. It can never be entirely eliminated. However, attenuators can be designed to reduce phase shift to a very low level, especially over narrow bandwidths.

HARMONICS AND IMD

Every PIN diode-based device generates some level of harmonics and intermodulation products because diodes are non-linear devices. In this regard, switched-BIT attenuators outperform analog voltage variable attenuators (VVAs) because switched-BIT attenuators are basically just PIN diode switches. That is, their diodes are biased either fully on or fully off.

POWER-HANDLING ABILITY

An attenuator's power-handling ability is dictated by its design, bias conditions, and switching speed. Generally speaking, faster VVAs handle less power, especially at low frequencies. An attenuator's maximum operating power level is defined as the amount of power required to cause 1 dB attenuation compression. At or near the 1 dB compression point, the attenuator will produce its highest levels of harmonics and intermodulation. Generally, the faster diodes will handle less power at lower frequencies because of the compression points dependence on I-layer thickness. The attenuator's survival rating is dictated by the diodes survival rating. As might be expected, attenuator power-handling specifications vary considerably and can be tailored to the needs of a specific application.

MONOTONICITY

This is a required attribute of any type of attenuator, regardless of the application. Without a monotonic attenuation relationship to the analog or digital control commands, the attenuator's accuracy and other characteristics can never be optimal. Non-monotonic behavior can be exhibited by switched-BIT attenuators as a result of uncompensated internal VSWR interaction, and in digitally-controlled analog attenuators with errors in digital calibration toward the band edges.

MEAN ATTENUATION

This parameter is the average of maximum and minimum values of attenuation over a given frequency range for a given control signal. It is of particular importance in wideband analog VVAs, as they typically have a parabolic attenuation vs. frequency response, and the minimum-to-maximum attenuation vs. frequency at higher levels can be as large as 5 dB in multi-octave designs.

ATTENUATION FLATNESS

The attenuation variation from the mean attenuation over a given frequency range for a given attenuation value is called attenuation flatness, and is expressed in dB.

ATTENUATION ACCURACY

This parameter is the maximum deviation of the mean attenuation from the nominal value of the programmed attenuation, expressed in dB.

COMPARISON OF ATTENUATOR CHARACTERISTICS

PARAMETERS	SWITCHED-BIT	DIGITALLY-LINEARIZED ANALOG
Switching speed	Very high (20 ns)	Moderate (>100 ns)
Attenuation accuracy	High	Highest
Attenuation flatness with frequency	Best	Moderate
Power handling	High	Moderate
Operating frequency bandwidth	Broad (2 to 3 octaves)	Moderate (1 octave)
Resolution	High (1 dB)	Highest (0.25 dB)
Calibration	Fixed	Selectable within unit
Cost	High	Moderate
Survival and compression power	High	Moderate

DIGITALLY-LINEARIZED ANALOG ATTENUATORS vs. SWITCHED-BIT ATTENUATORS

There are dozens of possible attenuator configurations, each one with its own unique characteristics that make it better suited for one application over another.

DIGITALLY-LINEARIZED ANALOG ATTENUATORS

Other than switched-BIT types, all attenuators are essentially analog devices. There are as many analog attenuator configurations as there are system applications that require them. This guide covers only digitally-linearized analog attenuators, shunt-mounted diode arrays, and switched-BIT attenuators, because they are the most common and versatile types.

Typical VVAs contain from one to four shunt-mounted diodes (Figure 8a). Adjusting the bias current changes the resistance of the PIN diodes, reflecting more of the RF signal, which produces the desired attenuation.

This approach is similar to a reflective switch because it presents a poor match at the input and output ports. Most VVAs of this type are built in pairs and mounted between 3 dB hybrids (Figure 8b). The reflected RF power is absorbed by the termination at the hybrids isolated port, presenting a good match at the VVAs input and output ports.

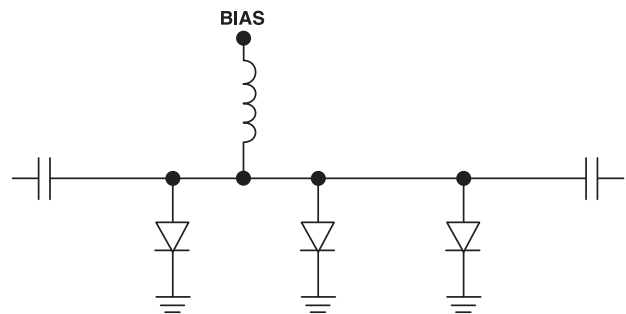


Figure 8a - Reflective

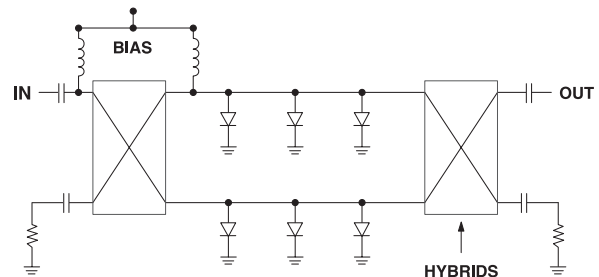


Figure 8b - Non-Reflective

An analog driver/linearizer or a digital driver (D/A converter with EPROM) can then be used to calibrate and linearize the VVAs attenuation vs. control signal response.

PIN DIODE ATTENUATORS (CONTINUED)

DIGITALLY-CONTROLLED SWITCHED-BIT ATTENUATORS

When broadband, ultra-fast switching performance is needed, the digitally-controlled switched-BIT attenuator is the only solution. It excels in attenuation accuracy and flatness over broad frequency ranges, and its switching speed is equivalent to a high-speed PIN diode switch (25 ns or better). Its only disadvantages are higher insertion loss and higher cost.

The digitally-controlled attenuators topology is based on switching-fixed attenuator pads in or out of the RF path using PIN diode SP2T switches. It uses one control BIT per attenuator pad, and attenuation step size is determined by the lowest attenuator pad value. The total attenuation range is the sum of all the attenuator pads.

As stated earlier, attenuators are designed to match the requirements of specific applications. When the application requires fast-switching speed combined with high power-handling ability (as in electronic warfare systems, for example), the switched-BIT attenuator is the optimum choice (Figure 9). It employs one or more pairs of SP2T switches, with a low-loss connection between one pair of outputs, and a fixed attenuator between the other outputs. The diodes are switched between their forward-bias and reverse-bias states, which gives the attenuator higher switching speed.

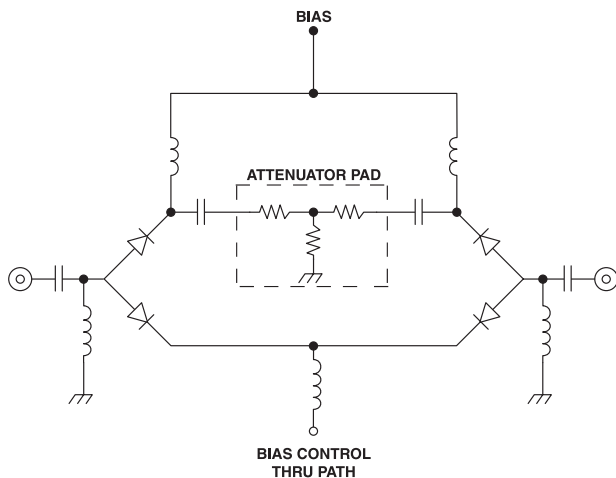


Figure 9 - Switched BIT attenuator

The switched-BIT attenuator achieves low, consistent VSWR performance throughout its dynamic range, and its power-handling ability (i.e., compression point and IMD) is also higher than that of an analog VVA because it uses PIN diode switches.

Of course, like all attenuator types, the switched-BIT attenuator has some disadvantages. Its smallest attenuation step size at microwave frequencies is limited to about 0.5 dB because of VSWR interaction among the various high-loss and low-loss transmission paths and their associated bias circuits. This interaction also causes attenuation ripple, which can cause slight degradations in monotonicity. These errors are usually less than about ± 0.5 dB.

Finally, the switched-BIT attenuator is a comparatively complex RF circuit with more components, and is usually more expensive. These considerations aside, the high-speed and power-handling abilities of the switched-BIT attenuator make it appealing for demanding applications.

LIMITERS

PIN diode limiters are designed to protect power-sensitive microwave components such as mixers, detectors, and amplifiers against damage from high-power CW and pulsed-microwave signals. Their specifications are always achieved through a compromise between operating frequency, input power and leakage.

Basic PIN diode limiters utilize shunt-mounted PIN diodes with relatively thin I-regions, resulting in low insertion loss at low-power levels. Power levels below the limiters threshold pass through the PIN diodes unattenuated. Insertion loss is a function of junction capacitance and parallel resistance in shunt with the transmission line, both of which are functions of diode geometry. As the input power increases above threshold, the diode starts to rectify the input power. Charge is injected into the diode, and if a DC return path is present, a DC current will be generated.

This current decreases the forward resistance of the diode, resulting in a progressive increase in attenuation, while output increases. At saturation, the diodes series resistance does not change with the rectified current, and output power will increase until the diode reaches its burnout temperature.

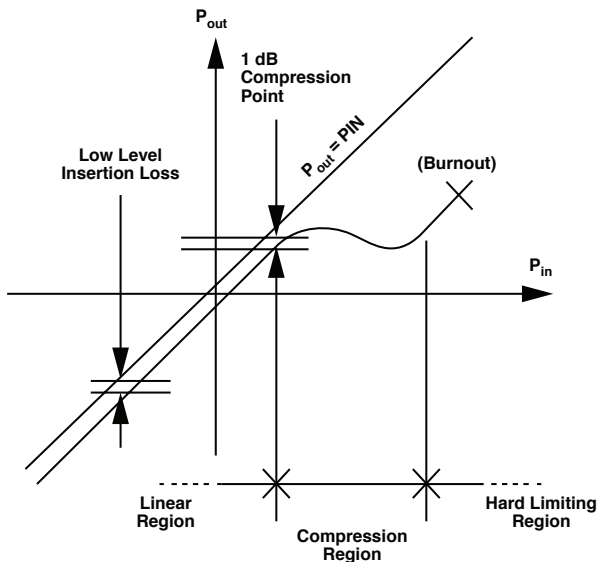


Figure 10 - Limiter operating characteristics

This limiting behavior is defined for typically three operating regions. In the linear region (low-incident power), the incident signal is passed with relatively little power loss. Insertion loss and VSWR are defined in this region. As the incident power level increases to the 1 -dB compression point, the limiter enters the compression region, where the RF power causes the PIN diodes to self-bias.

Continued increase in RF power level produce corresponding increases in attenuation until the diode reaches its saturation point. The limiter then provides almost constant, relatively high attenuation, and the output power will begin to increase in proportion to the input power. This is defined as the hard-limiting region. Eventually, thermal stresses on the PIN diodes lead to burnout. With pulsed input signals, additional

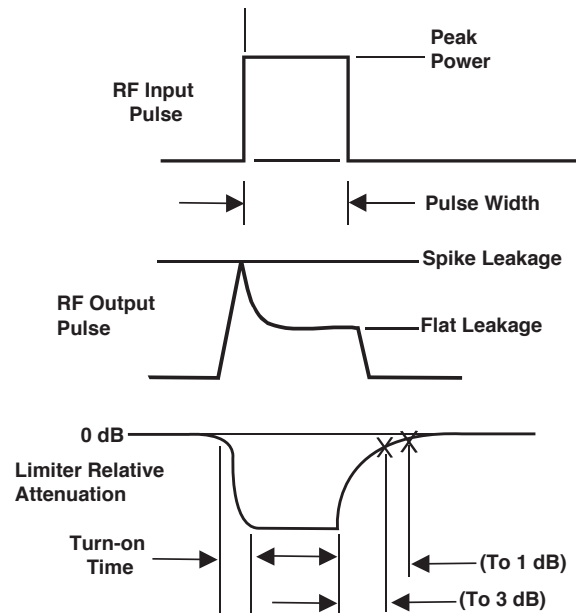


Figure 11 - Typical limiter pulse response

parameters are needed to fully describe the operation of PIN diode limiters. Of particular interest is the relationship of the input-pulse parameters to the output-pulse parameters and dynamic nature of a pulse input.

PIN DIODE LIMITERS

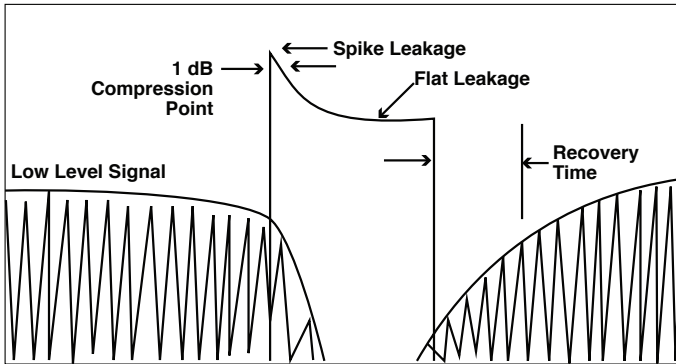


Figure 12 - Spike leakage

For a short period of time after pulsed high power is applied to the limiter, it will pass significantly more power than when it is totally saturated. The increase in power is a spike of energy on the leading edge of the leakage pulse (Figure 12). The rise time of the pulse and the turn-on time of the diode determine the amplitude of the spike, and they are difficult to measure because they depend on both the rise time of the incident pulse and the characteristics of the PIN diodes. The usual procedure is to specify spike leakage (measured in ergs), and calculate it as follows:

$$\text{Spike Leakage (ergs)} = t_s \times P_s \times 10^7$$

where:

t_s is the spike width at the half-power point (in seconds) and P_s is the maximum spike amplitude in watts.

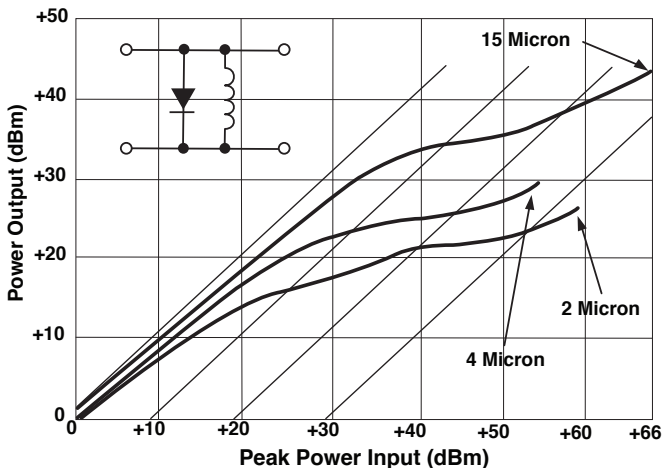


Figure 13 - Typical limiter performance vs. PIN diode I-layer thickness

Measurements of spike leakage are usually subjective unless attention is given to controlling the rise time of the incident pulse and the linearity of the detection system. After the limiter has fully turned on, the output pulse reaches a constant level, which is defined as the flat leakage level.

Power output remains at this level until the pulse ends or burnout occurs, depending on the amplitude of the input power. After the pulse is removed, it takes time for the limiter to return to its low-loss condition because of the intrinsic recovery time of PIN diodes. The limiter series resistance at saturation determines the maximum isolation of the limiter diode.

Increasing the I region thickness of the diode results in an increase in threshold and leakage power. This is illustrated in Figure 13 for diodes with base widths of 2 μm , 4 μm , and 15 μm . Above the threshold level, the limiter diode is very reflective. Some of the RF signal is reflected and some is absorbed when the diode is limiting. The relationship between input power and dissipated power is:

$$P_{\text{diss}} = \frac{P_{\text{in}} \cdot 200 \cdot R_s}{(50 + 2R_s)^2}$$

where:

R_s is the resistance of the diode in self-biased limiting mode.

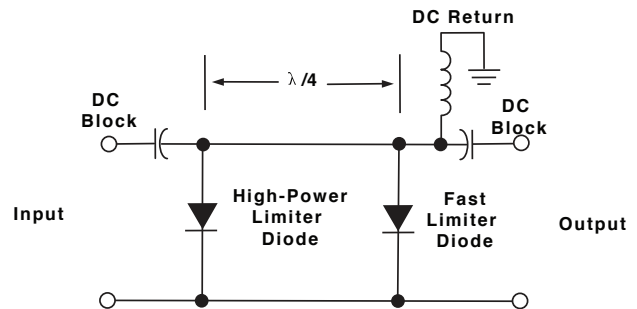


Figure 14 - Basic two diode limiter

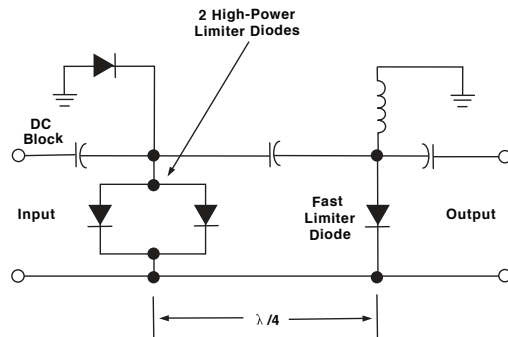


Figure 15 - Limiter with Schottky barrier diode lightly coupled to line

Limiting capability can be improved by adding a second limiter diode (Figure 14). In the basic two diode limiter, the first diode is chosen for the ability to handle the expected input RF power because it is subjected to all the pulse energy. This diode is followed by the clean-up diode, which has a lower breakdown voltage. The low-breakdown diode gets turned on by the spike leakage, which helps turn on the slower diode. The clean-up diode also provides attenuation of the RF leakage from the first diode. Output power (leakage power) of this two-stage scheme is determined by the selection of the clean-up diode.

In order to reduce leakage power below +10 dBm, a PIN-schottky limiter is often used (Figure 15). The Schottky diode is turned on first since the forward voltage is about 300 mV. This voltage biases the PIN diode. This scheme produces a limiter with a lower leakage power but a longer recovery time because although the Schottky diodes turn-on and turn-off times are very short, there is no DC return path for the PIN diode to discharge.

For higher peak and CW power-handling ability, dual high-power PIN diodes (preferably fabricated from the same chip) are used, followed by medium-power and clean-up limiter diodes.

ADDITIONAL LIMITER CONSIDERATIONS

In addition to the specifications just described, there are others that must be considered when specifying a limiter for a particular application.

RECOVERY TIME

This represents the transition from high-loss to the low-loss state following the removal of a high-power input. It is defined as the time from the end of a high-power pulse to the time when insertion loss has returned to within 3 dB of the quiescent (low-power) state.

POWER-HANDLING ABILITY

When specifying a limiter, two important considerations are its peak-pulsed power-handling ability and its source VSWR. For narrow pulses, peak-pulsed power equates to an equivalent CW power by multiplying the peak power and the duty cycle. When the pulse is longer than 10 μ s, the peak power is considered CW.

The limiter is short circuit across the transmission line when it is fully turned on and up to 90 percent of the incident power is reflected back towards the source. Any mismatch at the source will reflect power back to the limiter, causing standing waves on the line. If the limiter-source phase relationship is correct a maximum current point will occur at the input diode in the limiter, causing the diode to dissipate much more power than the incident power level would indicate. By multiplying the source VSWR by the incident power the maximum effective power can be obtained for a source VSWR of up to 2.1

GLOSSARY

GLOSSARY

Absorptive Device – A device in which the specified VSWR is maintained and all power is absorbed in the device during the high-loss state.

Accuracy/Linearity – In voltage-variable attenuators, the variation of the mean attenuation from the best straight line of attenuation vs. control signal transfer function.

Analog Attenuator – A unit in which attenuation level is controlled either by an applied current in a driverless unit or by a voltage in a unit with a driver. Attenuation level is continuously variable.

Attenuation Accuracy – The deviation of mean attenuation from the nominal attenuation value at a specified temperature (usually room temperature).

Bias – The control voltage or current signals supplied to a unit that provide proper operation for devices without integral drivers.

Carrier Suppression – The minimum ratio of carrier output power to the translated carrier output power in a phase shifter operated as a frequency translator.

Commutation – With all other ports set to isolation, one port is switched from insertion loss to isolation, while another port is switched from isolation to insertion loss. This specification applies only to multi-throw switches.

Digitally-Controlled Voltage-Variable Attenuator (VVA) – An analog attenuator with an integral driver in which control inputs are logic bits. Attenuation is not continuously adjusted, but is selected in steps. The steps are defined by the number of bits employed by the device, the maximum attenuation of the unit, and the logic levels applied to it.

Driver – The circuit used to convert analog or logic command signals to the bias conditions needed to execute control of active devices.

Fall Time – A measure of switching speed represented by the time between the 90 percent and 10 percent points of the detected RF power, when the unit is switched from insertion loss (on) to isolation (off).

Insertion Loss – The difference, measured in dB, between input power level and output power level when the unit is in a low-loss condition.

Isolation – The difference, measured in dB, between input power level and output power level when a unit is in a high-loss condition.

Mean Attenuation – The average attenuation over an attenuator's range of operating frequencies.

Modulation – With all other ports set to isolation, one port is repeatedly switched on and off.

Modulation Bandwidth – The maximum repetition rate at which a device can be switched.

Monotonicity – As the control input level is increased, the attenuation level continuously increases. At no point in the range does an increase in control input cause a decrease in attenuation at any frequency or value of attenuation.

Off Time – A measure of switching speed represented by the time between the 50 percent point of input control pulse to the 10 percent point of detected RF power, when the unit is switched from insertion loss (on) to isolation (off).

On Time – A measure of switching speed represented by the time between the 50 percent point of input control pulse to the 90 percent point of detected RF power, when the unit is switched from isolation (off) to insertion loss (on).

Operating Frequency Range – The band of frequencies over which the product must operate and deliver specified performance.

Operating Power (Power Handling) – The maximum power over which a unit will achieve specified performance.

Operating Temperature Range – The temperature range over which a unit will achieve specified performance.

Phase and Amplitude Matching – The maximum range of values within which all phase or amplitudes are controlled over a specified frequency range. Usually referenced to one port and measured from port-to-port or unit-to-unit.

Phase Shift – The difference in electrical phase of a signal from the input of the device to its output. Measured as absolute insertion phase, or with respect to a given state. In a phase shifter, the difference in phase angle of an RF signal at a given frequency and phase-shift setting. Referenced to the emitted signal at the same frequency with the phase shifter set to 0 degrees phase shift.

Reflective Device – A device in which the incident power is reflected back to the source when the port is in the high-loss state.

Rise Time – A measure of switching speed represented by the time between the 10 percent and 90 percent points of the detected RF power, when the unit is switched from isolation (off) to insertion loss (on).

Sideband Suppression – The minimum ratio of any sideband output power to the translated carrier output power when a phase shifter is operated as a frequency translator.

Survival Power – The maximum RF power level to which a unit can be subjected without permanent performance degradation or failure.

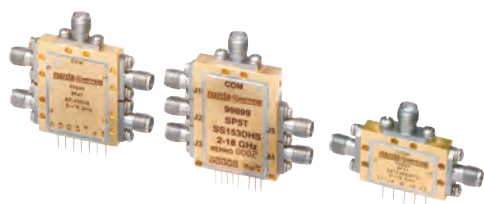
Switching Speed – Either modulation or commutation. All specifications, unless otherwise noted, in the Narda-MITEQ catalog, are modulation switching speed.

Temperature Coefficient – The average rate of change in phase shift (degree phase shift/°C) or attenuation change (dB/°C) over the entire operating temperature range of the unit.

Translation Rate – When a digital phase shifter is used as a frequency translator, the clock rate divided by the number of steps determines the translation. When N equals the number of phase BITS, the number of phase steps is equal to 2^N .

VVA Linearity – In a voltage-variable attenuator, the variation from straight-line attenuation vs. control signal level.

SWITCHES



SUPER-SLIM HIGH-PERFORMANCE DROP-IN PIN SWITCHES

- Reflective and Absorptive
- SPST thru SP6T and Transfer (Standard)
- High Speed
- High Isolation – up to 80 dB
- Low-Insertion Loss
- Drop-In Applications
- Integral TTL Drivers
- Hermetically Sealed
- Full-MIL-Specifications

DESCRIPTION

The super-slim series of broadband, hermetically sealed switches offers fast-switching speed and low-insertion loss in very compact packages. Both 0.5 GHz to 18 GHz and 2 GHz to 18 GHz models are available. The switches are gold plated and have removable SMA connectors for use in drop-in applications. Superior RF performance is achieved over the entire bandwidth due to the use of selected PIN diodes and optimum RF circuit designs.

All models include integral drivers with reverse voltage protection. The drivers are TTL compatible and are tailored to each RF circuit to give optimum switching performance.

The small size, high-speed, broad bandwidth and low-insertion loss make these switches ideal for EW systems, automatic test equipment and simulators.



HIGH-PERFORMANCE PIN SWITCHES

- Reflective and Absorptive
- SPST thru SP6T and Transfer (Standard)
- High Speed - 15 ns
- High Isolation – up to 80 dB
- Low-Insertion Loss
- Small Package Size
- Integral TTL Drivers
- Hermetically Sealed
- Full-MIL-Specifications

DESCRIPTION

The performance series of 0.5 GHz to 18 GHz and 2 GHz to 18 GHz hermetically sealed switches offers fast-switching speed and low-insertion loss in compact packages. These switches use the identical circuits employed in Narda-MITEQ's top-of-the-line Super-Slim Series. They are ideal for connectorized applications where the absolutely thinnest profile is not required.

All models include integral drivers with reverse voltage protection. The drivers are TTL compatible and are tailored to each RF circuit to give optimum switching performance.

The small size, high-speed, broad bandwidth and low-insertion loss make these switches ideal for EW systems, automatic test equipment, and simulators.

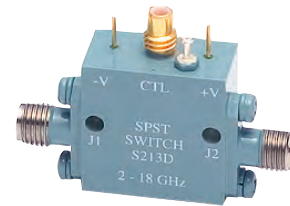


HIGH-PERFORMANCE MINIATURE SWITCHES

- 2 GHz to 18 GHz
- Very Small Package Size
- AVANPAK equivalents
- Reflective
- SPST and SP2T
- Low-Insertion Loss
- Integral TTL Drivers
- Hermetically Sealed

DESCRIPTION

These miniature switches are ideal for applications where size is critical. They are direct replacements for AVANPAK™ Models with equal or better specifications.



3 WATT PIN SWITCHES

- 2 GHz to 18 GHz
- 3 Watt CW
- High Speed
- Low-Insertion Loss
- High Isolation
- Small Size
- Hermetically Sealed

DESCRIPTION

These SPST and SP2T switches are hermetically sealed high-speed PIN switches that provide high isolation, low VSWR and insertion loss. Special attention has been given to high-packaging density for military environments.



SPST / SP2T PIN SWITCHES

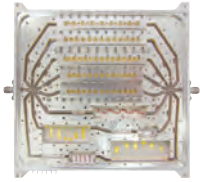
- 0.1 GHz to 40 GHz
- Reflective
- Hermetically Sealed
- Full-MIL-Specifications



CUSTOM MULTI-THROW ABSORPTIVE PIN DIODE SWITCHES

- 0.5 GHz to 18 GHz
- Custom Capability
- Reflective and Absorptive
- Couplers, Power Dividers and Amplifiers included
- Hermetically Sealed
- Full-MIL-Specifications

FILTER BANK LIMITERS



SWITCHED FILTER BANKS

- Custom Designs
- Fast Switching Speed
- Low-Insertion Loss
- Small Size
- Cavity, Lumped Element and Printed Filters available

DESCRIPTION

A switched filter bank is comprised of SPNT input and output switches together with a series of filters for every channel. Narda-MITEQ's switched filter banks are built as an integral unit of switches, filters and drivers.

These switched filter banks are custom designed to customer specifications, including the package configuration. The following are some examples of units that have been designed and manufactured.



LIMITERS

- 1 GHz to 18 GHz
- Connectorized and Drop-In Modules
- High-Power Ratings
- Fast Recovery Time
- Small Size
- Hermetically Sealed
- Full-MIL-Specifications

DESCRIPTION

Narda-MITEQ offers a wide range line of PIN diode-based limiters designed to meet severe environmental conditions for airborne as well as other applications. Broadband limiters cover up to 1 GHz to 18 GHz in one band and support power handling of up to 500 watts of pulsed power. The narrowband limiters cover typically 25 percent frequency band within the frequency range of up to 18 GHz. They support power handling of up to 400 watts of pulsed power.



HIGH-POWER SWITCHES

- High-Power Handling
- Low-Insertion Loss
- High Isolation
- TTL Control
- Fast Switching

DESCRIPTION

The Narda-MITEQ series of reliable broadband high-power solid-state switches to cover a myriad of applications which include ground, airborne, transmit/receive, filter banks, as well as complex high-power switch matrices. Offering both standard and custom designs, Narda-MITEQ's switches cover the frequency ranges from 2 GHz to 18 GHz in octave and multi-octave bandwidths up to 1000 watts. Our high-power switches offer fast-switching speeds, while providing the extremely high reliability that is expected of a product.

SPECIFICATIONS

Most of our high-power switches are built to customer specifications in order to optimize specific parameters such as: long pulses, switching speed, isolation and high CW power. So if you require broadband, high speed and high isolation, long pulses or high CW operating power, Narda-MITEQ can meet your needs.

HIGH-SPEED



HIGH-SPEED SWITCHED-BIT ATTENUATORS

- Very High Speed
- Precise Attenuation over Frequency Band
- Small Package Size
- Low-Insertion Loss
- Hermetically Sealed

Options Available Based On Standard Designs

- Different Attenuation Range
- Performance Optimized over a Narrower Bandwidth
- Reverse Logic Control

DESCRIPTION

These miniature, high-speed digitally-controlled switched-BIT attenuators are designed for operation over multi-octave bandwidths. Attenuation levels are guaranteed to be monotonic and selectable using standard TTL logic circuitry. All models are hermetically sealed and are specified to operate over the full temperature range. All attenuators are equipped with removable RF connectors and are suitable for drop-in applications.

DIGITALLY-CONTROLLED ATTENUATORS (DCAs) vs. VOLTAGE-VARIABLE ATTENUATORS (VVAs)

A VVA allows the user to select any value within its rated attenuation range – the user has full analog control. Most VVAs operate by changing the bias current of the series and shunt PIN diodes that form attenuator pads. This design approach leads to significant errors in attenuation level over the operating bandwidth. The most demanding system requirements can only be met by using a look-up table to correct for these errors.

DCAs provide very precise attenuation levels in digital (binary) increments. They have extremely fast-

switching speeds compared to VVAs – typically ten to twenty times faster. These switched-BIT attenuators combine one or more tandem pairs of SP2T PIN diode switches with a zero-loss connection between one pair of outputs and a fixed attenuator inserted in the other. The PIN diodes are simply switched between their forward and reverse states, rather than being used as variable attenuators. Very high-speed PIN diodes and control circuitry are used to operate all the BITS in parallel.

The major disadvantages of DCAs vs VVAs are the minimum practical attenuation level, higher cost due to more complex circuits, somewhat higher insertion loss, and the potential for video leakage due to the high-speed switches. The smallest practical least significant BIT is about 0.5 dB. Video filters can often be incorporated into the DCA to satisfy specific leakage requirements.



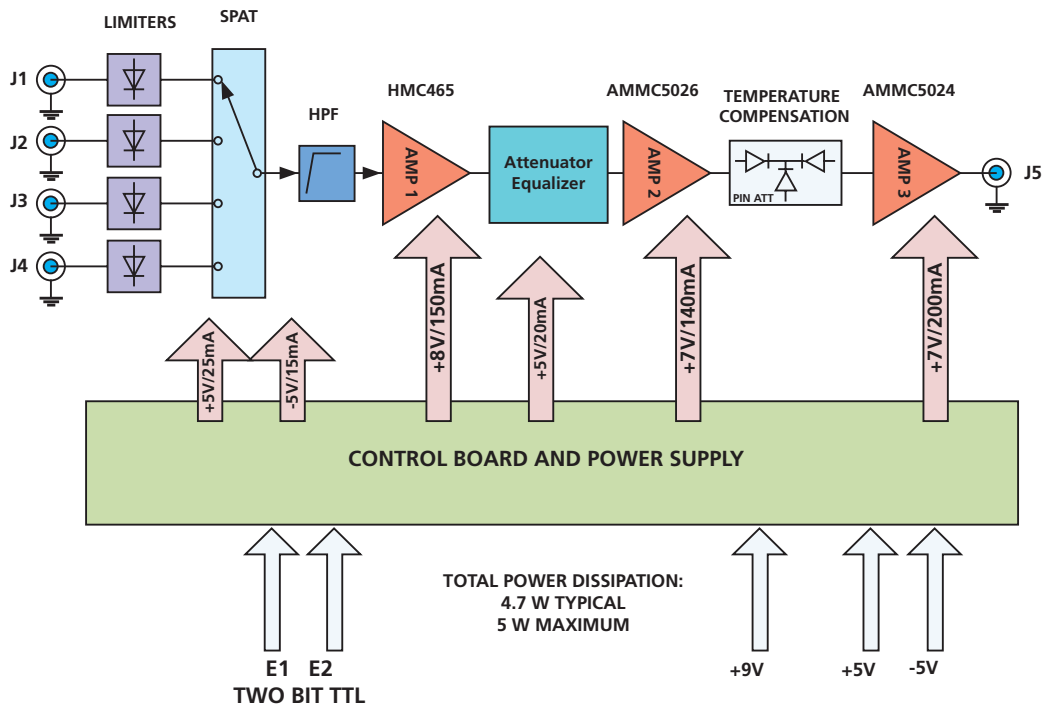
DESCRIPTION

This device is a RF IMA (Integrated Microwave Assembly) made up of limiters, switches, high-pass filter, low-noise amplifiers and gain, temperature and equalization compensation.

PIN DIODE BASED IMAs

One example of custom designs:

- Frequency Range:2 GHz to 18 GHz
- Logic Control:4 BIT TTL
- Gain:26 dB to 30 dB
- Noise Figure:8 dB maximum
- Input RF Power:2 W CW, 200 W Peak
- Selectable 1 of 4 Inputs to 1 Output
- Hermetically Sealed



PIN DIODE CONTROL PRODUCTS

The material presented in this datasheet was current at the time of publication. Narda-MITEQ's continuing product improvement program makes it necessary to reserve the right to change our mechanical and electrical specifications without notice. If either of these parameters is critical, please contact the factory to verify that the information is current.

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